



Material Content Data Sheet



Sales Product Name		IPD95R2K0P7		Issued		9. January 2019		
MA#		MA001831316						
Package		PG-TO252-3-341		Weight*		387.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.666	0.43	0.43	4298	4298
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		177	
	non noble metal	iron	7439-89-6	0.229	0.06		591	
	non noble metal	copper	7440-50-8	228.946	59.08	59.16	590631	591399
	non noble metal	aluminium	7429-90-5	0.402	0.10	0.10	1037	1037
wire	non noble metal	aluminium	7429-90-5	0.402	0.10	0.10	1037	1037
encapsulation	organic material	carbon black	1333-86-4	0.393	0.10		1013	
	plastics	epoxy resin	-	11.915	3.07		30738	
	inorganic material	silicondioxide	60676-86-0	118.628	30.60	33.77	306033	337784
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9648	9648
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1313	1313
solder	non noble metal	tin	7440-31-5	0.039	0.01		100	
	noble metal	silver	7440-22-4	0.048	0.01		125	
	non noble metal	lead	7439-92-1	1.844	0.48	0.50	4757	4982
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		50	
	non noble metal	copper	7440-50-8	19.177	4.95	4.95	49474	49539
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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